Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 7500 1.2T Fabric IRF-only MPU (JH207A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
Socket Spanner	
Continuous vacuum desoldering system	
Desoldering tip	
Damp sponge	
Flux-cored solder	
tweesers	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove film 1 from assembly 2;
2. Remove shielding finger 3 from panel 2;
3. Unscrew the screws on assembly 4,then remove assembly 4 from assembly 2;
4. Unscrew the screws on plate 4-1,and then remove plate 4-1;
5. Remove pins on heatsink 4-2,and then remove heatsink 4-2 from PCB 4-7;
6. Remove screws on heatsink 4-3,and then remove heatsink 4-3;
7. Remove screws on plate 4-4,and then remove plate 4-4;
8. Remove hexagonal bolt 4-5 on PCB 4-6,and then remove PCB 4-6;
9. Remove all hexagonal bolts 2-2 on front panel 2-1;
10. Remove heatsink 2-4 on PCB 2-3;
11. Unscrew the screws on strengthening bar 2-5,then remove 2-5;
12. Unscrew the screws on guiding sets 2-6,then remove guiding sets 2-6;
13. Remove battery according to figure 4~figure 8

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

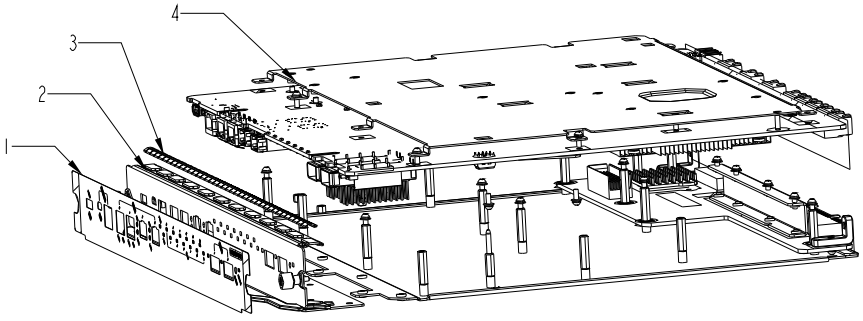

Figure1 Treatments to the product

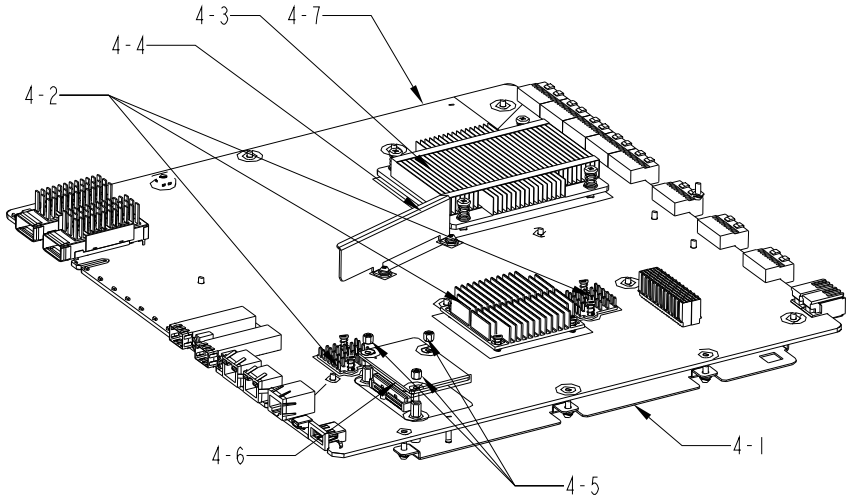

Figure 2 Treatments to the assembly 4

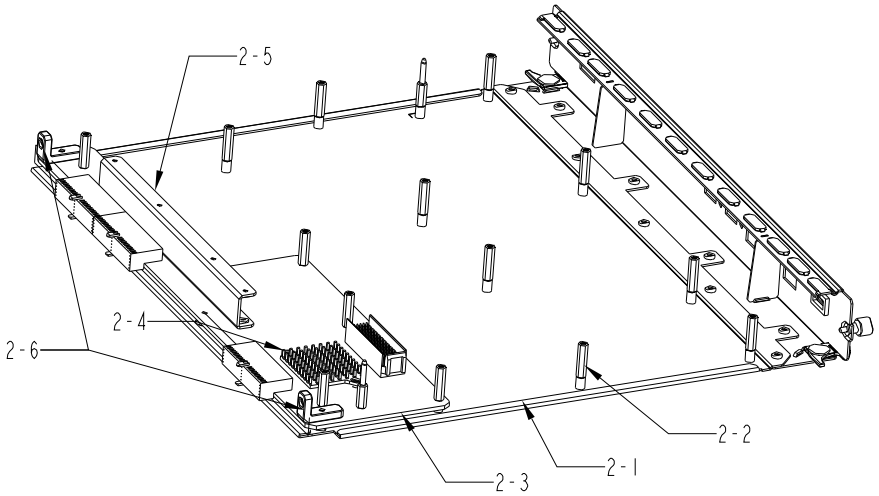

Figure 3 Treatments to the assembly 2

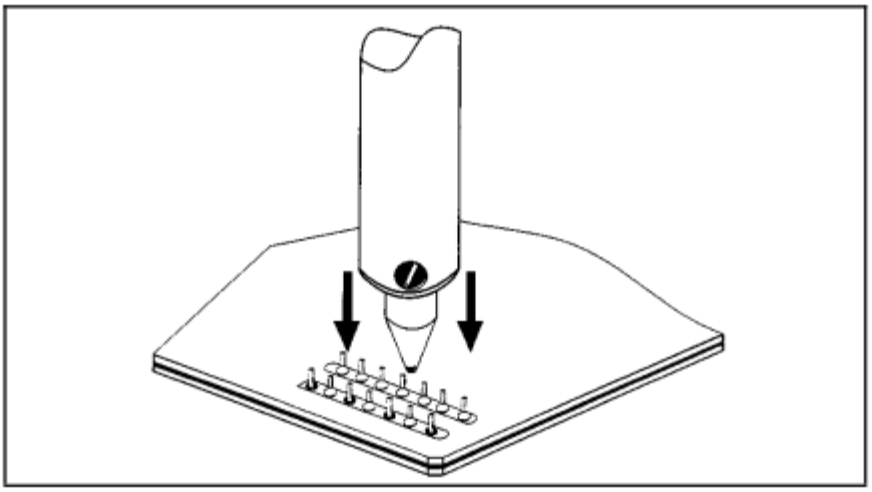

Figure 4 Position Tip

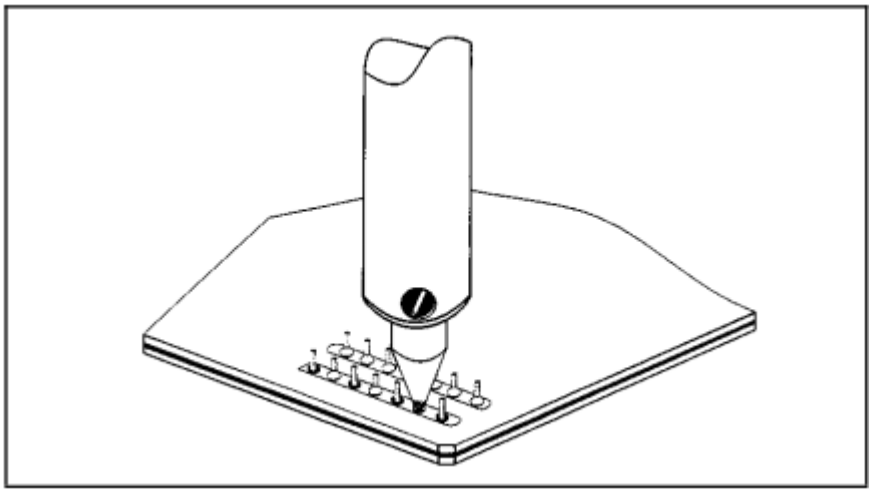

Figure 5 Melt Solder

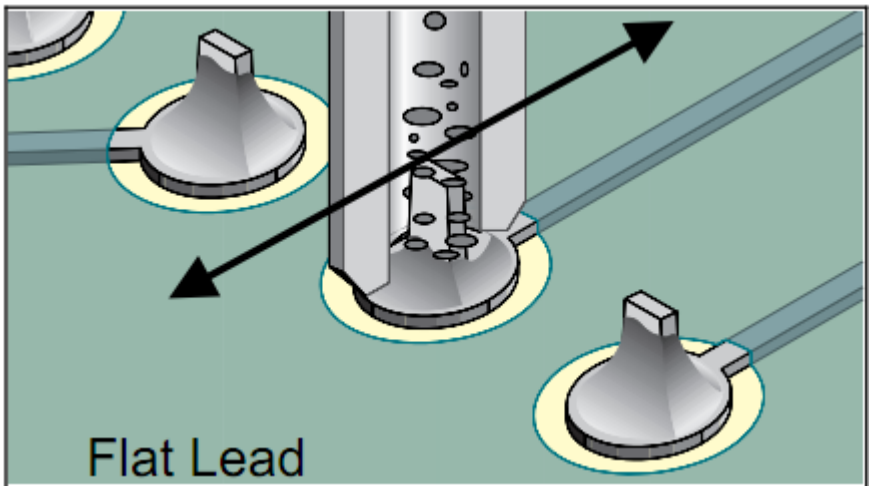

Figure 6 Move Lead & Apply Vacuum

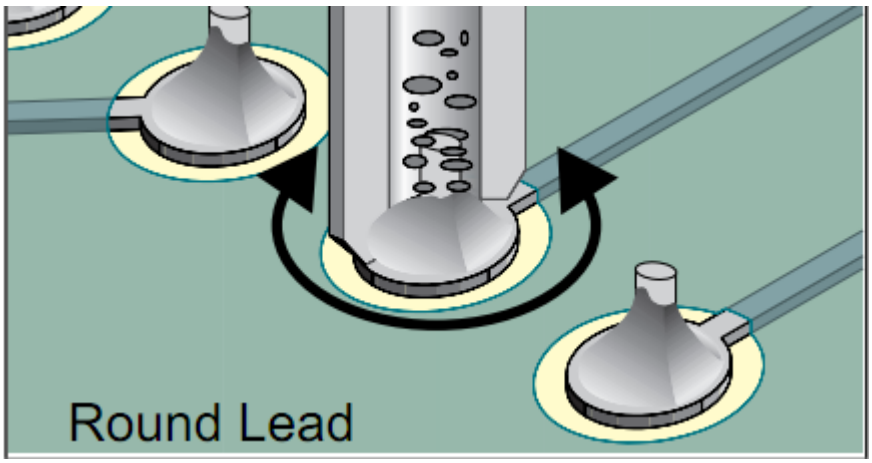

Figure 7 Move Lead & Apply Vacuum

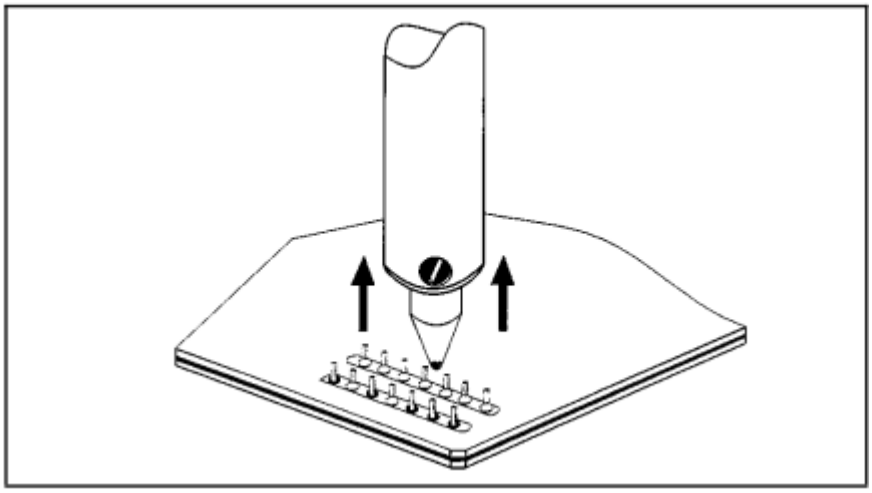

Figure 8 Lift Handpiece

3.3 Material of the facility built

Facility	Components	Material	Weight (g)	Weight percentage	Selective treatment for materials and components	Details
1		PC	4.4	0. 10%		Pla recycling
2	2-1	Fe	1577	36.66%		Fe recycling
	2-2	Cu	67.2	1.56%		Cu recycling
	2-3	Complex PWB	233.3	5.42%	The surface lf PCB is greater than 10 square centimeters	
	2-4	Al	9.3	0.22%		Al recycling
	2-5	Fe	92.7	2.15%		Fe recycling
	2-6	Al	9.0	0.21%		Al recycling
3		Be-Cu	2.7	0.06%		Cu recycling
4	4-1	Fe	726.0	16.88%		Fe recycling
	4-2	Al	49.3	1.15%		Al recycling
	4-3	Al	317.2	7.37%		Al recycling
	4-4	Fe	24.2	0.56%		Fe recycling
	4-5	Cu	2.1	0.05%		Cu recycling
	4-6	Complex PWB	11.7	0.27%	The surface lf PCB is greater than 10 square centimeters	
	4-7	Complex PWB	1175.7	27.33%	The surface lf PCB is greater than 10 square centimeters	

4. Revised record

Date	Version	Author	Modify content
2015.06.25	V0	Liao Wenqing	Initial version